Serial No. 10/797,456
Atty. Doc. No. 2003P13760US

In The Claims:

1 (Currently Amended). Semi-conducting thin sheet wedges comprising:
a mica matrix, wherein said mica matrix comprises mica flakes; and
a conductive resin impregnated within said mica matrix;
wherein said thin sheet wedges have a semi-conductive property of between 500-500,000 ohms per square, wherein said conductive resin comprises a resin and conductive particles.

2 (Original). The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges have a thickness of between about 15-80 mils (0.38-2.0 mm).

3 (Original). The semi-conducting thin sheet wedges of claim 1, wherein said mica flakes comprise at least one of muscovite, phlogopite and combinations thereof.

4 (Original). The semi-conducting thin sheet wedges of claim 1,wherein said resin comprises approximately 15-40% by weight of said thin sheet wedges.

5 (Currently Amended). The semi-conducting thin sheet wedges of claim 1, wherein said resin ~~is~~ comprises C-black.

6 (Original). The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges have a tensile modulus of between 1-8 million PSI.

7 (Original). The semi-conducting thin sheet wedges of claim 1, wherein said thin sheet wedges further comprises at least one glass fiber layer.

8 (Original). The semi-conducting thin sheet wedges of claim 7, wherein the ratio of the mica in said mica matrix to the glass fiber is approximately between 2:1 and 7:1 by weight.

9 (Original). The semi-conducting thin sheet wedges of claim 7, wherein said at least one glass fiber layer forms a backing for said mica matrix.

10 (Original). The semi-conducting thin sheet wedges of claim 7, wherein said at least one glass fiber layer is interwoven with said mica matrix.

11 (Original). The semi-conducting thin sheet wedges of claim 10, wherein said at least one glass fiber layer is interwoven in a half-lap manner.

12 (Currently Amended). Semi-conducting thin sheet wedges comprising:

a mica matrix, wherein said mica matrix comprises mica flakes;

at least one layer of glass fiber; and

a conductive resin impregnated within at least one of said mica matrix and said at least one layer of glass fiber, wherein said conductive resin comprises a resin and conductive particles;

wherein said thin sheet wedges have a semi-conductive property of between 500-500,000 ohms per square;

wherein said thin sheet wedges have a tensile modulus of between 1-8 million PSI.

13 (Original). The semi-conducting thin sheet wedges of claim 12, wherein the ratio of the mica in said mica matrix to the glass fiber is approximately between 2:1 and 7:1 by weight.

14 (Original). The semi-conducting thin sheet wedges of claim 12, wherein said at Least one glass fiber layer forms a backing for said mica matrix.

15 (Original). The semi-conducting thin sheet wedges of claim 12, wherein said at least one glass fiber layer is interwoven with said mica matrix.

16 (Original). The semi-conducting thin sheet wedges of claim 15, wherein said at least one glass fiber layer is interwoven in a half-lap manner.

17 (Original). The semi-conducting thin sheet wedges of claim 12, wherein said mica flakes comprise at least one of muscovite, phlogopite and combinations thereof.

18 (Original). The semi-conducting thin sheet wedges of claim 12, wherein said resin comprises approximately 15-40% by weight of said thin sheet wedges.

19 (Currently Amended). The semi-conducting thin sheet wedges of claim 12, wherein said resin ~~is~~ comprises C-black.

20 (Currently Amended). A method for making semi-conductive thin sheet wedges comprising:

layering a mica matrix onto a glass fiber backing, wherein said mica matrix comprises mica flakes;

impregnating into said mica matrix and said glass fiber a conductive resin, wherein said conductive resin comprises a resin and conductive particles; and

curing said conductive resin.